TMDSSK3358 Board

- See the Hardware User Guide for board details
- See the Board Errata document for important details
- See the PCB Build Specification for PCB Details
SD/MMC Connector
Decaps  
Power SEL  
Pull ups  
PHY Address  
BootStrapping

Decaps
- VETH_VDD1,2,3
- VETH_VPH2

Power SEL
- VETH_VIDEO
- VETH_VPH2

Pull ups
- ETH0_INT
- ETH0_RST
- ETH0_RST
- ETH0_RST

PHY Address
- PHYADDRESS = 00001

BootStrapping
- MODE SELECTION
  - Mode "0000" = 1000 BASE-T, RGMII
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